



Product Change Notification - RMES-08UJCE505

Date:

02 Jun 2020

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3718 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of the 35.4K wafer technology available in 44L VQFN package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of the 35.4K wafer technology available in 44L VQFN package at NSEB assembly site.

Pre Change:

Assembled using gold (Au) bond wire and G770HCD molding compound material.

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire and G700LTD molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (NSEB)	UTAC Thai Limited (NSEB)
Wire material	Au	CuPdAu
Die attach material	8600	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	EFTEC 64T	EFTEC 64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and G700LTD molding compound material.

Change Implementation Status:

In Progress



Estimated First Ship Date:

July 2, 2020 (date code: 2027)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2019					-->	June 2020				July 2020				
Workweek	09	10	12	13	14		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date				X											
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date											X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

March 28, 2019: Issued initial notification.

June 2, 2020: Issued final notification. Attached the qualification report. Provided the estimated first ship date to be July 2, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-08UJCE505_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATMEGA324PHBL-B15MT

ATMEGA324P-B15MZ

ATMEGA164P-B15MZ